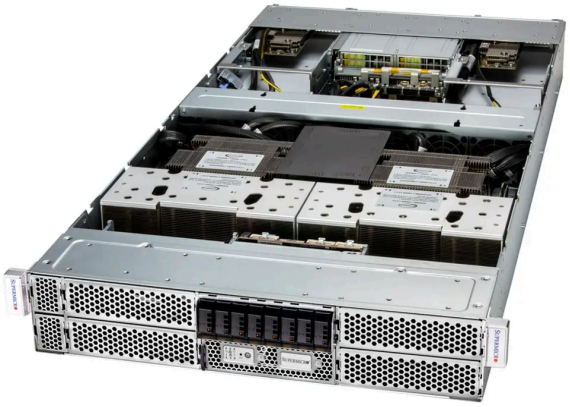
Arm-based (ARS) | 2U Rackmount | GPU Server

Supermicro ARS-221GL-NHIR

Arm-based (ARS) · 2U Rackmount · GPU Server Server

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Form Factor **2U Rackmount**	CPU **NVIDIA 72-core NVIDIA Grace CPU on GH200 Grace Hopper™ Superchip**
GPU **2 onboard GPUs**	Memory **Onboard Memory**

Key Features

- High density 2U 1-node GPU system with two Integrated NVIDIA H100 GPUs and two 72-core Arm Neoverse V2 CPUsNVIDIA® NVLink® high speed interconnect between both GH200 Super Chips
- NVIDIA Grace™ Hopper Superchip (Grace CPU and H100 GPU)
- NVLink® Chip-2-Chip (C2C) high-bandwidth, low-latency interconnect between CPU and GPU at 900GB/s
- Up to 1248GB of coherent memory (system as a whole), including 960GB LPDDR5X and 288GB of HBM3e for LLM applications
- 3x PCIe 5.0 X16 supporting one NVIDIA Bluefield 3 and two connectX-7 cards
- 6 Heavy Duty Fans with Optional Speed Control

Form Factor	2U Rackmount
Platform	Arm-based (ARS)
CPU	NVIDIA 72-core NVIDIA Grace CPU on GH200 Grace Hopper™ Superchip
Max GPU Count	2 onboard GPUs
Supported GPU	NVIDIA: H100 Tensor Core GPU on GH200 Grace Hopper™ Superchip (Air-cooled)
Memory	Onboard Memory 960GB ECC LPDDR5X
Drive Bays	Default: Total 3 bays3 front fixed E1.S NVMe drive bays
Fans	Up to 6 Removable heavy-duty 6cm Fan(s)
Power Supply	4x 2000W Redundant (2 + 2) Titanium Level (96%) power supplies

Full Specifications — ARS-221GL-NHIR

Motherboard

Motherboard	ARS-221GL-NHIR Super G2DMH-GI

Processor

CPU	NVIDIA 72-core NVIDIA Grace CPU on GH200 Grace Hopper™ Superchip
Core Count	72C/72T; 114MB Cache per CPU
Note	Supports up to 300W TDP CPUs (Air Cooled)

GPU

Max GPU Count	2 onboard GPUs
Supported GPU	NVIDIA: H100 Tensor Core GPU on GH200 Grace Hopper™ Superchip (Air-cooled) View GPU Options
CPU-GPU Interconnect	NVIDIA NVLink®-C2C
GPU-GPU Interconnect	NVIDIA® NVLink™

System Memory

Memory	Onboard Memory 960GB ECC LPDDR5X Additional GPU Memory: 288GB ECC HBM3e

On-Board Devices

Chipset	GH200
Network Connectivity	View AOC Options

Input / Output

LAN	1 RJ45 1 GbE Dedicated BMC LAN port
USB	1 port (Rear)
Video	1 mini-DP port

System BIOS

BIOS Type	AMI 64MB UEFI

Management

Power configurations	Power-on mode for AC power recovery ACPI Power Management

PC Health Monitoring

CPU	Monitors for CPU Cores, Chipset Voltages, Memory
Fan	Fans with tachometer monitoring Pulse Width Modulated (PWM) fan connectors Status monitor for speed control
Temperature	Monitoring for CPU and chassis environment Thermal Control for fan connectors

Certifications

Operating Systems	RHEL 9.4 View all OS Compatibility and Certification Matrix

Chassis

Form Factor	2U Rackmount
Model	CSE-MG202TS-R000NDFP

Dimensions and Weight

Height	3.43" (87 mm)
Width	17.3" (438.4 mm)
Depth	35.43" (900 mm)
Package	11.02" (H) x 27.56" (W) x 47.24" (D)
Weight	Gross Weight: 103 lbs (46.8 kg) Net Weight: 88 lbs (40 kg)
Available Color	Silver

Front Panel

Buttons	Power On/Off
LED	HDD activity

Expansion Slots

PCI-Express (PCIe) Configuration	Default3 PCIe 5.0 x16 (in x16) FHFL slots 1 PCIe 5.0 x4 (in x16) FHFL slot View AOC Options

Drive Bays / Storage

Drive Bays Configuration	Default: Total 3 bays3 front fixed E1.S NVMe drive bays
M.2	2 M.2 NVMe slots (M-key) View M.2 Options

System Cooling

Fans	Up to 6 Removable heavy-duty 6cm Fan(s)

Power Supply

4x 2000W Redundant (2 + 2) Titanium Level (96%) power supplies

Dimension (WxHxL)	73.5 x 40 x 185 mm
Input	1000W: 100-127Vac / 50-60Hz 1800W: 200-220Vac / 50-60Hz 1980W: 220-230Vac / 50-60Hz 2000W: 230-240Vac / 50-60Hz 2000W: 220-240Vac / 50-60Hz (for UL only) 2000W: 230-240Vdc / 50-60Hz (for CQC only)
+12V	Max: 83A / Min: 0A (100Vac-127Vac) Max: 150A / Min: 0A (200Vac-220Vac) Max: 165A / Min: 0A (220Vac-230Vac) Max: 166A / Min: 0A (230Vac-240Vac)
12V SB	Max: 3.5A / Min: 0A
Output Type	Backplanes (gold finger)

Operating Environment

Environmental Spec.	Operating Temperature: 10°C to 35°C (50°F to 95°F) Non-operating Temperature: -40°C to 60°C (-40°F to 140°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)